

2SK3736

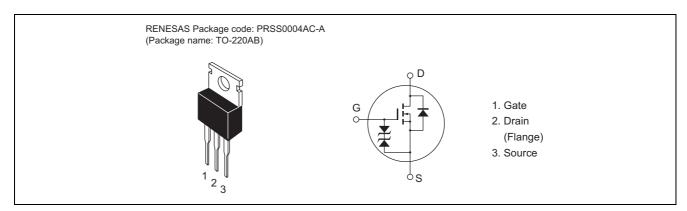
Silicon N Channel MOS FET Power Switching

REJ03G0525-0200 Rev.2.00 Jul 27, 2006

Features

- Capable of 2.5 V gate drive
- Low drive current
- Low on-resistance

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	250	V
Gate to source voltage	V _{GSS}	±10	V
Drain current	I _D	6	A
Drain peak current	I _D (pulse) Note1	24	A
Body-drain diode reverse drain current	I _{DR}	6	A
Channel dissipation	Pch ^{Note2}	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

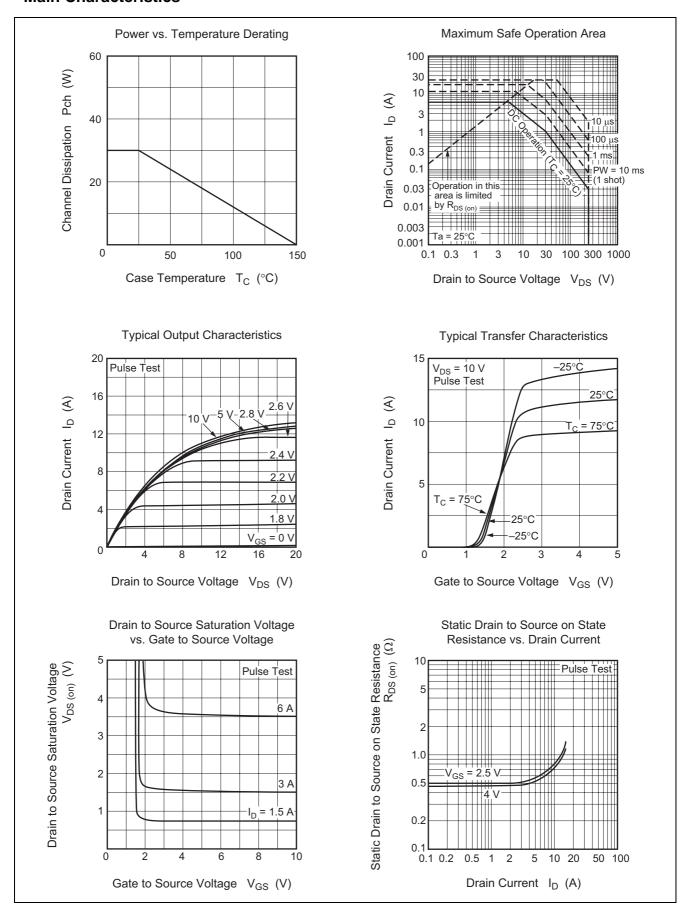
Electrical Characteristics

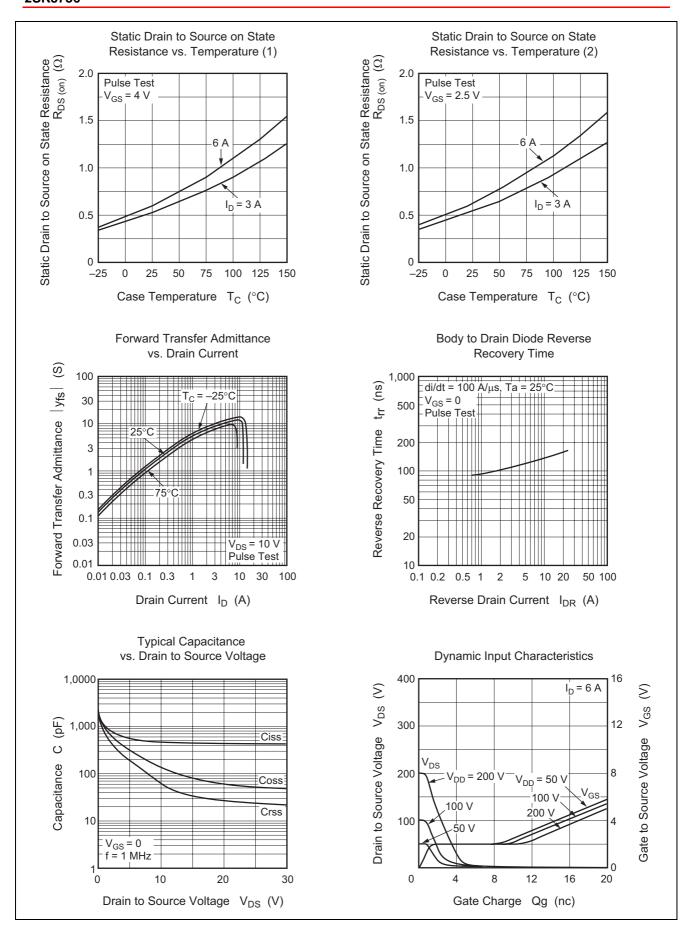
 $(Ta = 25^{\circ}C)$

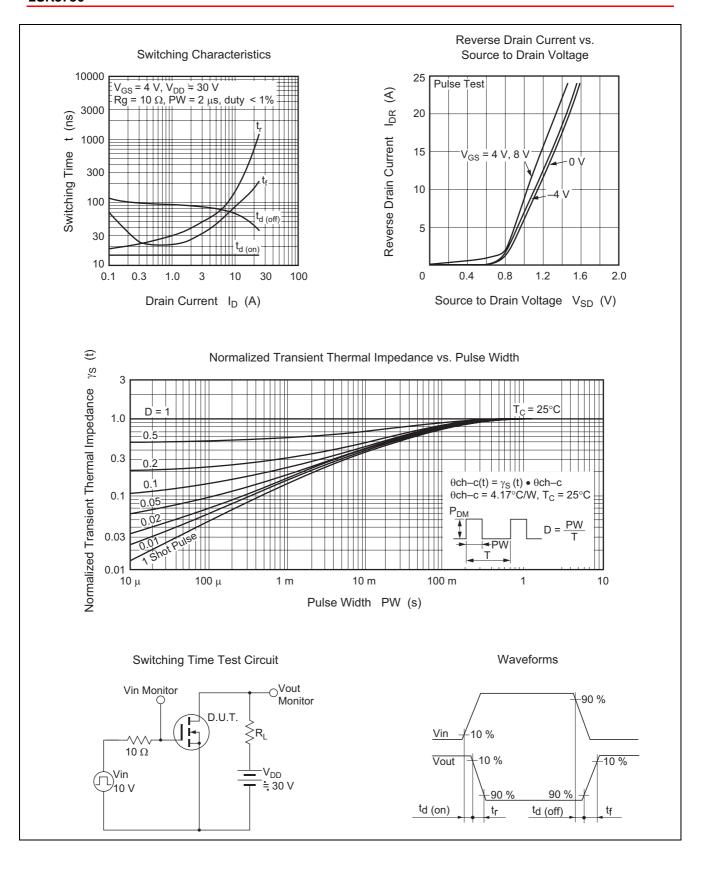
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	250	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±10	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	1	_	±10	μΑ	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	1	_	5	μΑ	$V_{DS} = 250 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	0.5	_	1.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state	R _{DS(on)}	_	0.55	0.7	Ω	$I_D = 3 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note3}}$
resistance	R _{DS(on)}	_	0.57	0.8	Ω	$I_D = 3 \text{ A}, V_{GS} = 2.5 V^{\text{Note3}}$
Forward transfer admittance	y _{fs}	5.5	9.2	_	S	$I_D = 3 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Output capacitance	Ciss	_	450	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	100	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	60	_	pF	
Total gate charge	Qg	_	17	_	nC	$V_{DD} = 200 \text{ V}, V_{GS} = 4 \text{ V},$
Gate to source charge	Qgs	_	0.8	_	nC	$I_D = 6 A$
Gate to drain charge	Qgd	_	9.5	_	nC	
Turn-on delay time	t _{d(on)}	_	14	_	ns	$V_{GS} = 4 \text{ V}, I_{D} = 3 \text{ A},$
Rise time	t _r	_	48	_	ns	$R_L = 10 \Omega$, $Rg = 10 \Omega$
Turn-off delay time	t _{d(off)}	_	88	_	ns	
Fall time	t _f	_	25	_	ns	
Body-drain diode forward voltage	V_{DF}	_	0.94	1.45	V	$I_F = 6 \text{ A}, V_{GS} = 0^{\text{Note3}}$
Body-drain diode reverse recovery time	trr	_	125		ns	$I_F = 6 \text{ A}, V_{GS} = 0$ di _F /dt = 100 A/µs

Notes: 3. Pulse test

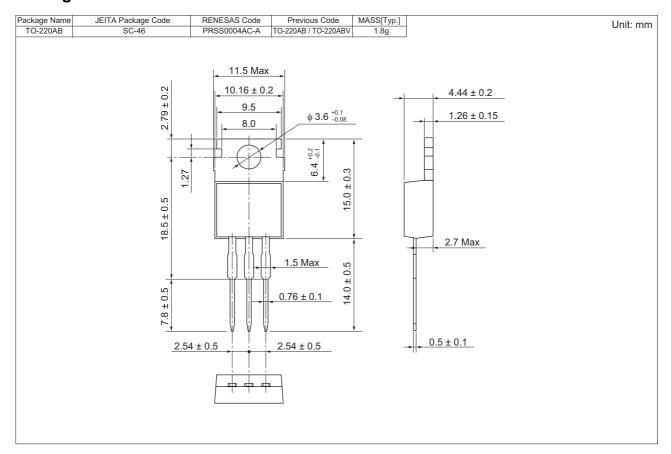
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK3736	50 pcs.	Sack

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Renesas Technology Malaysia Sdn. Bhd
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